



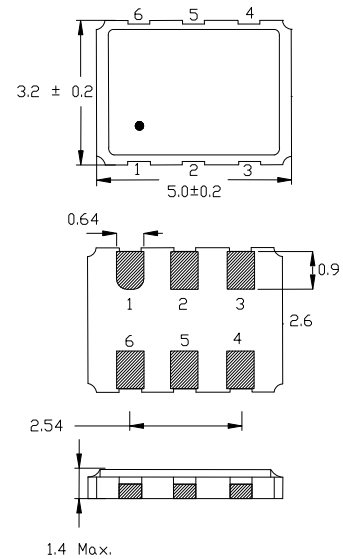
Product Features:

- Surface Mount Package
- Low Jitter
- Reflow Compatible
- Compatible with Leadfree Processing

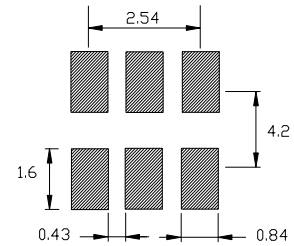
Applications:

- Test Equipment
- Server & Storage
- Sonet /SDH

Frequency	25 MHz to 350.000 MHz
Output Level	$V_{OH} = V_{CC} - 1.02$ VDC Min. $V_{OL} = V_{CC} - 1.62$ VDC Max.
Duty Cycle	50% \pm 5%
Rise / Fall Time	1.0 nS Max.
Output Load	50 Ω to $V_{CC} - 2.0$ VDC
Frequency Stability	\pm 25ppm
Enable Phase Delay	2 mS Max.
Disable Phase Delay	200 nS Max.
Supply Voltage	See Input Voltage Table, Tolerance \pm 5 %
Current	55 mA Typical, 90 mA Max.
Operating	0° C to +70° C
Storage	-40° C to +85° C
Integrated Jitter RMS	0.3 typ. (12 KHz to 20 MHz Band)



Recommended Pad Layout



- | | |
|-----|--------------|
| Pin | Connection |
| 1 | Enable |
| 2 | N.C. |
| 3 | Vss |
| 4 | Output |
| 5 | Comp. Output |
| 6 | VDD |

Dimension Units: mm

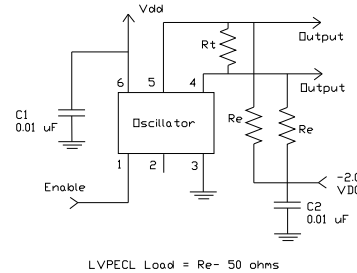
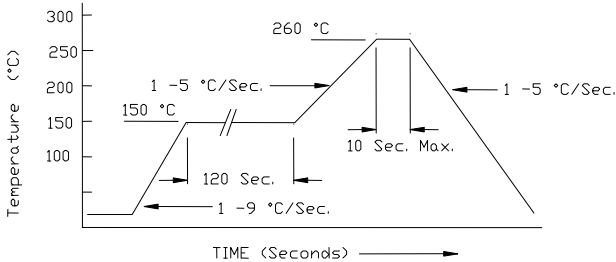
Part Number Guide		Sample Part Number:		ISM88 – 3159AH - 156.250			
Package	Input Voltage	Operating Temperature	Symmetry (Duty Cycle)	Output	Stability (in ppm)	Enable / Disable	Frequency
ISM88 -	3 = 3.3 V	1 = 0° C to +70° C	5 = 45 / 55 Max.	9 = LVPECL	A = \pm 25*	H = Enable	- 156.250 MHz
	6 = 2.5 V	2 = -40° C to +85° C			Z = \pm 30		
					B = \pm 50		
					C = \pm 100		

NOTE: A 0.01 μ F bypass capacitor is recommended between Vcc (pin 6) and GND (pin 3) to minimize power supply noise. * Not available for all temperature ranges and frequencies.



Pb Free Solder Reflow Profile:

Typical Application:

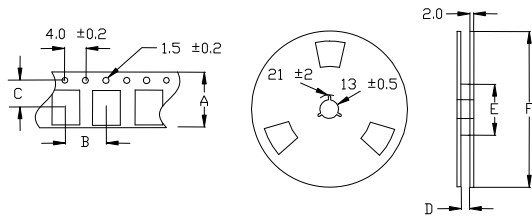


*Units are backward compatible with 240C reflow processes

Package Information:

MSL = N.A. (package does not contain plastic, storage life is unlimited under normal room conditions).
Termination = e4 (Au over Ni over W base metalization).

Tape and Reel Information:



Quantity per Reel	1000
A	16 +/- .3
B	8 +/- .2
C	7.5 +/- .2
D	17.5 +/- .1
E	50 / 60 / 80
F	180 / 250

Environmental Specifications

Thermal Shock	MIL-STD-883, Method 1011, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A
Resistance to Soldering Heat	J-STD-020C, Table 5-2 Pb-free devices (except 2 cycles max)
Hazardous Substance	Pb-Free / RoHS / Green Compliant
Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Terminal Strength	MIL-STD-883, Method 2004, Test Condition D
Gross Leak	MIL-STD-883, Method 1014, Condition C
Fine Leak	MIL-STD-883, Method 1014, Condition A2, R1=2x10 ⁻⁸ atm cc/s
Solvent Resistance	MIL-STD-202, Method 215

Marking

Line 1: ILSI and Date Code (YWW)
Line 2: Frequency

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